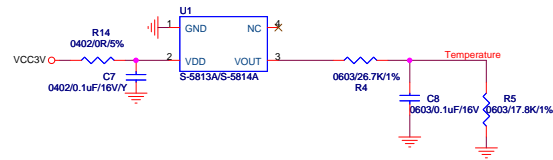
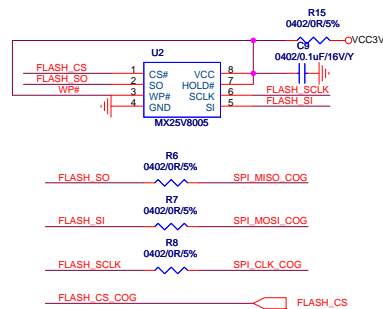


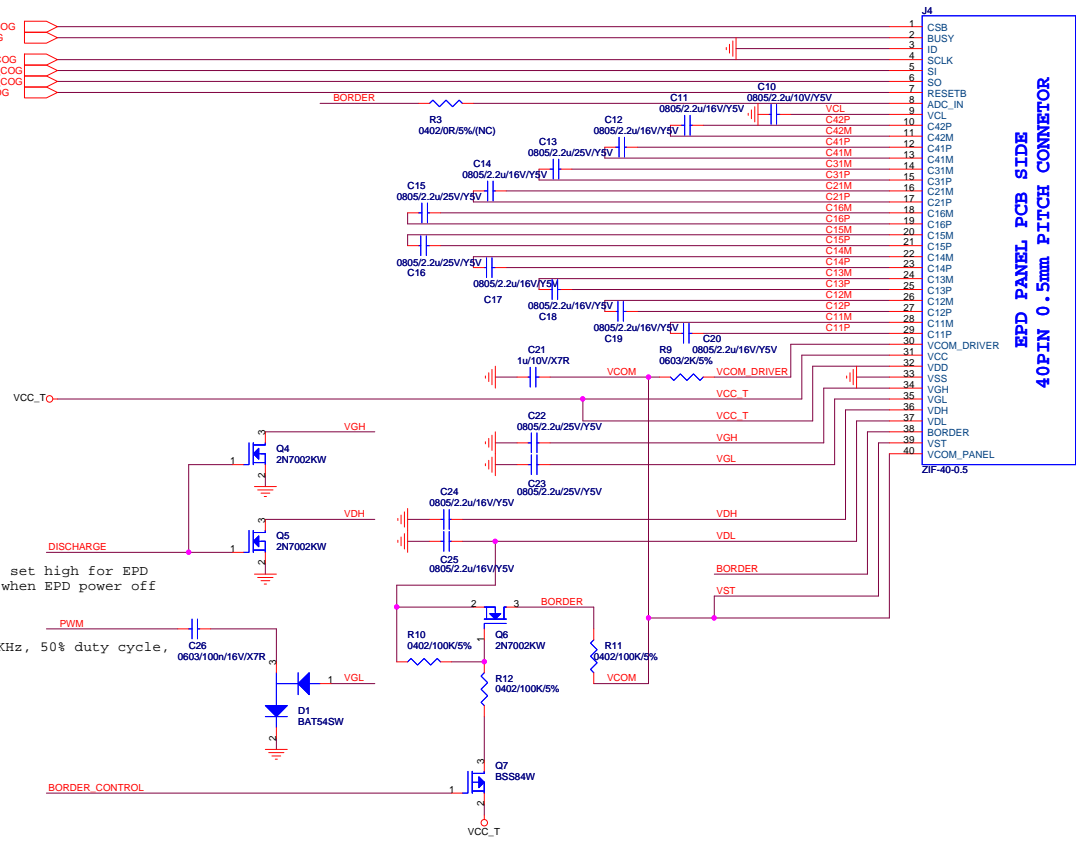
### Temperature Sensor



### Serial Flash 8M-bit



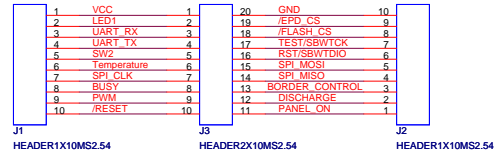
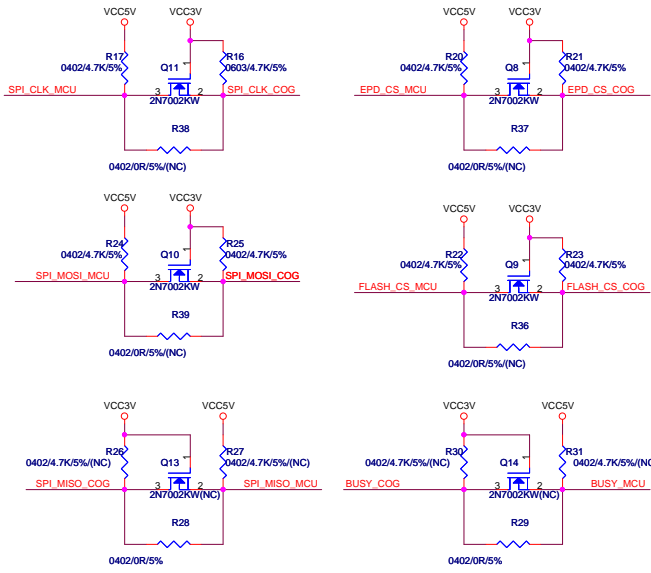
EPD\_CS\_COG  
BUSY\_COG  
SPL\_CLK\_COG  
SPL\_MOSI\_COG  
SPL\_MISO\_COG  
RESET\_COG



EPD PANEL PCB SIDE  
40PIN 0.5mm PITCH CONNECTOR

DISCHARGE: set high for EPD discharge when EPD power off

PWM: 100-300KHz, 50% duty cycle, square wave

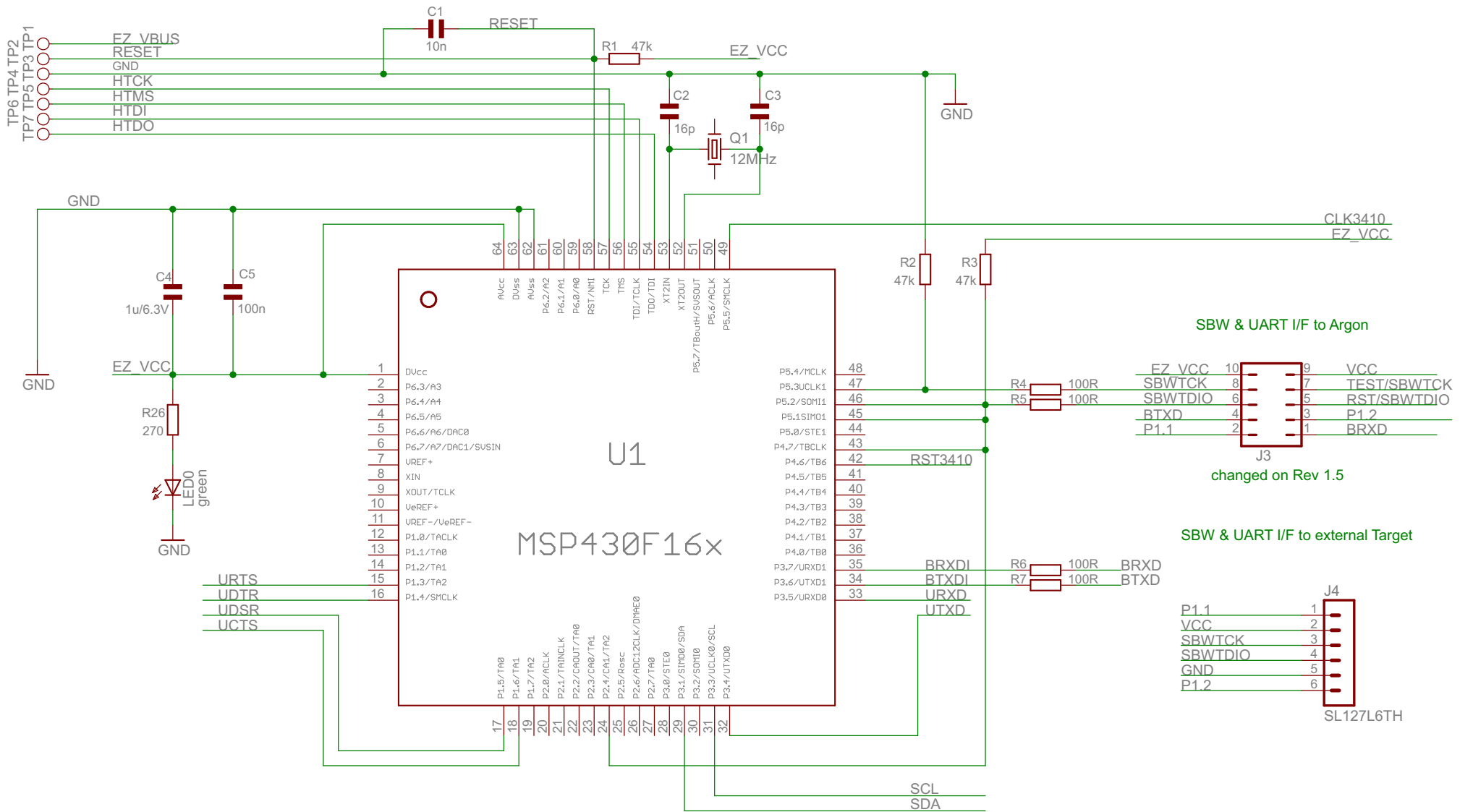


VCC5V - VCC  
EPD\_CS\_MCU - /EPD\_CS  
FLASH\_CS\_MCU - /FLASH\_CS  
RESET\_MCU - /RESET  
BUSY\_MCU - BUSY  
SPL\_CLK\_MCU - SPI\_CLK  
SPL\_MOSI\_MCU - SPI\_MOSI  
SPL\_MISO\_MCU - SPI\_MISO

**PERVASIVEDISPLAYS** 龍亨科技股份有限公司

APPROVED:	Date:	DWG NO.:
CHECKED:	Date:	PART NO.:
DESIGNER:	Date:	Rev SHEET: 3 1
DRAWER:	Date:	Title <b>EPD extension board v5</b>
A		TOP 01

Tuesday, February 05, 2013



### MSP-EXP430G2 EMULATOR 1/2

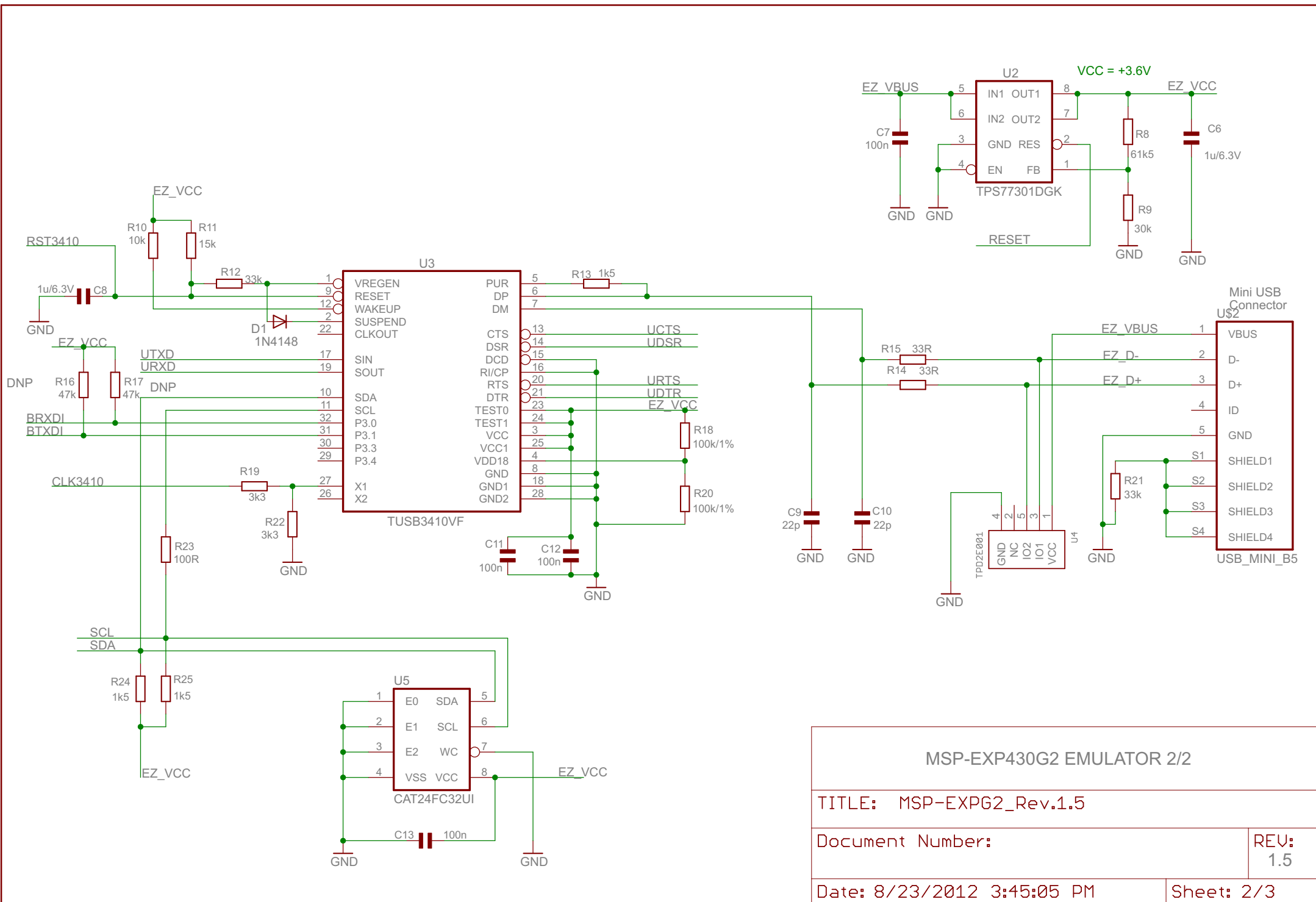
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Document Number:

REV:  
1.5

Date: 8/23/2012 3:45:05 PM

Sheet: 1/3

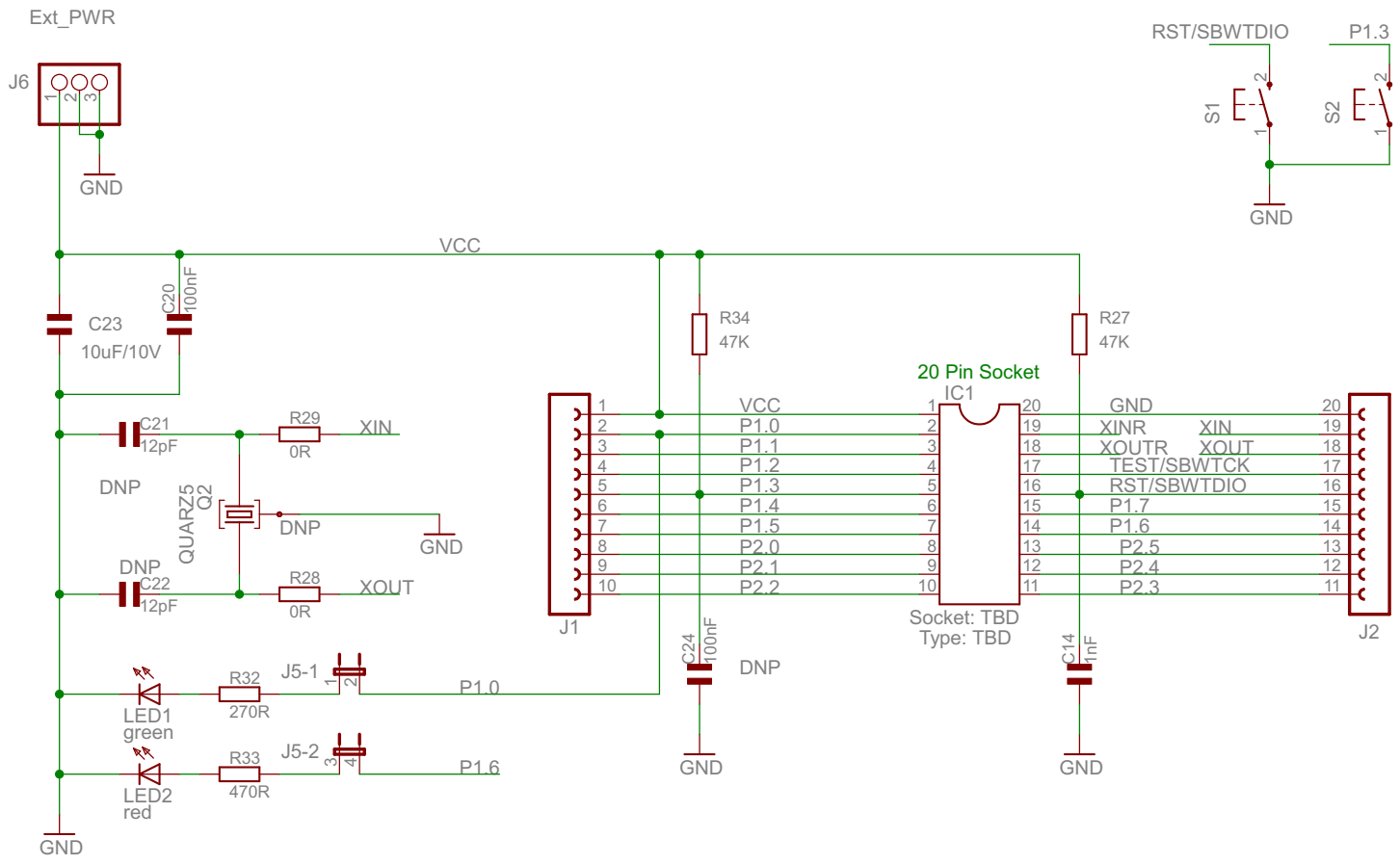


### MSP-EXP430G2 EMULATOR 2/2

TITLE: MSP-EXP62\_Rev.1.5

Document Number: REV: 1.5

Date: 8/23/2012 3:45:05 PM Sheet: 2/3



MSP-EXP430G2 TARGET SOCKET

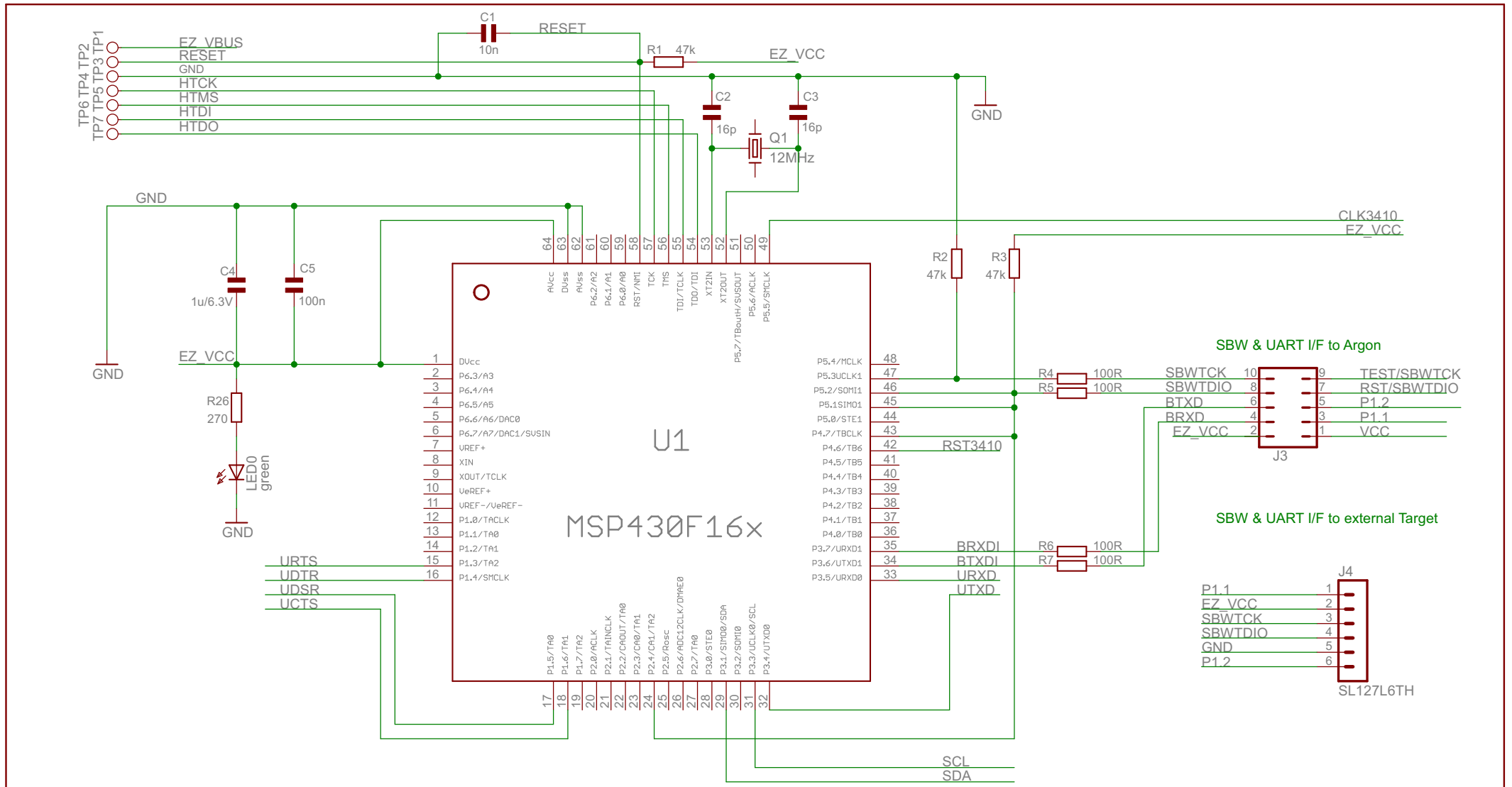
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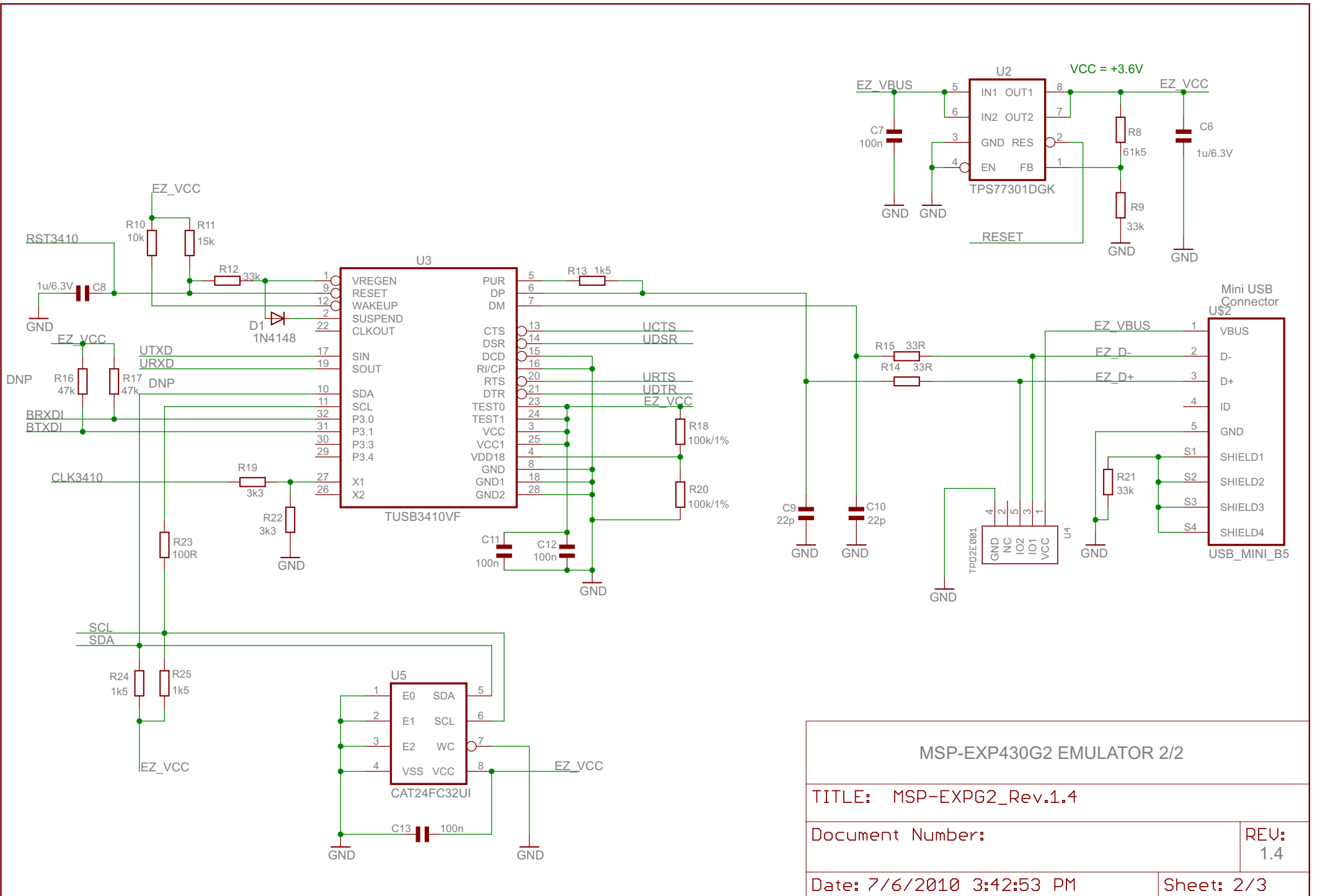
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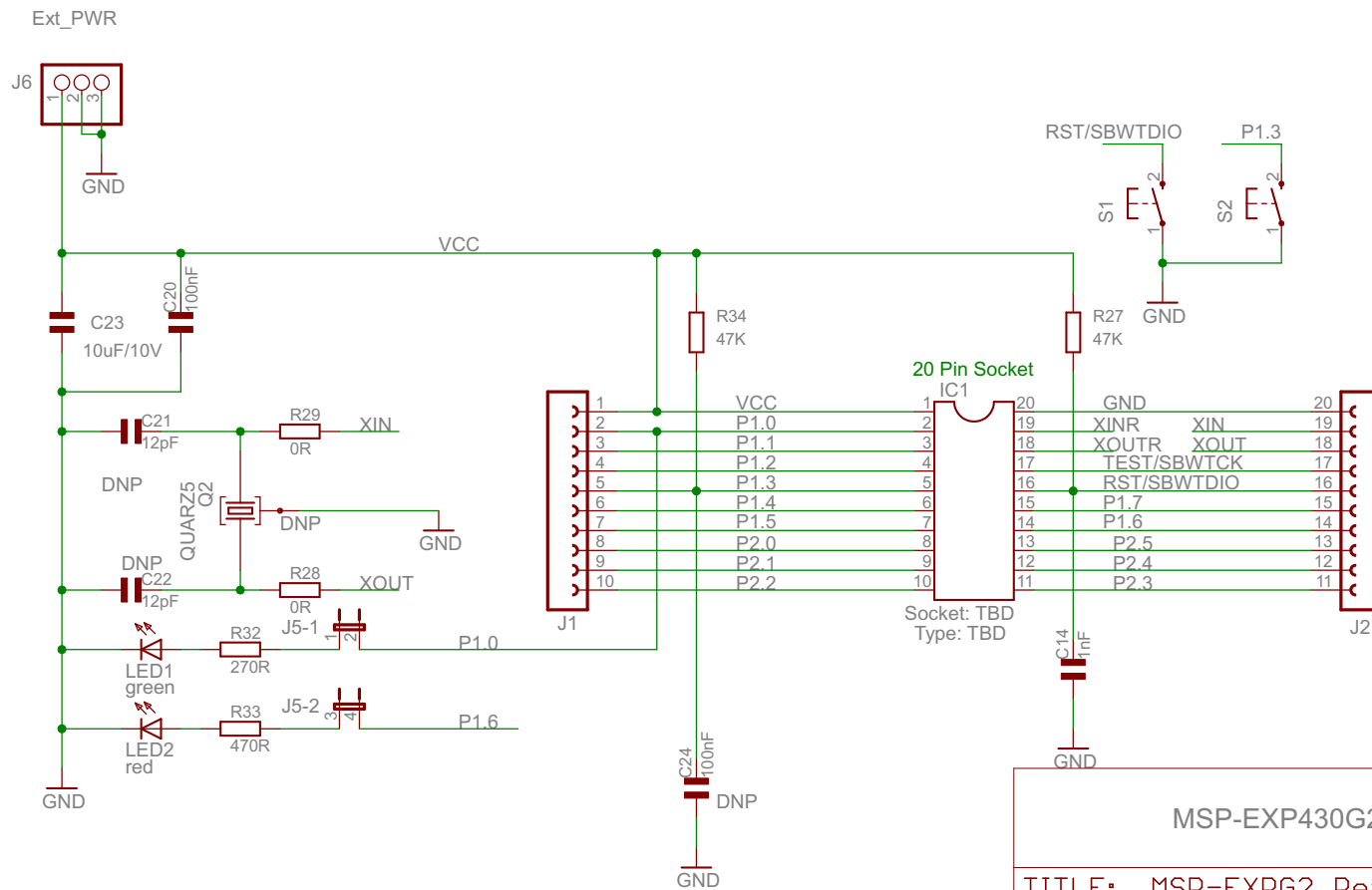
Sheet: 3/3



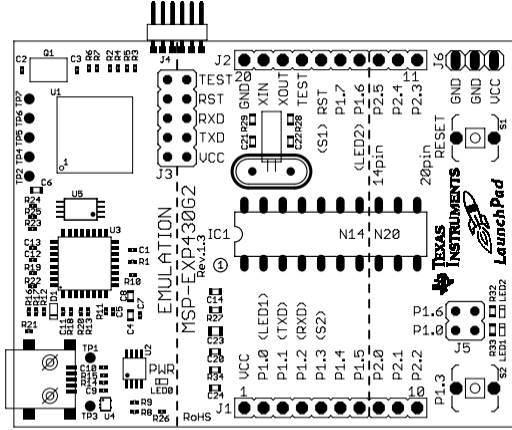
Removed U2: SN75240PW from SBW connections

MSP-EXP430G2 EMULATOR 1/2	
TITLE: MSP-EXPG2_Rev.1.4	
Document Number:	REV: 1.4
Date: 7/6/2010 3:42:53 PM	Sheet: 1/3

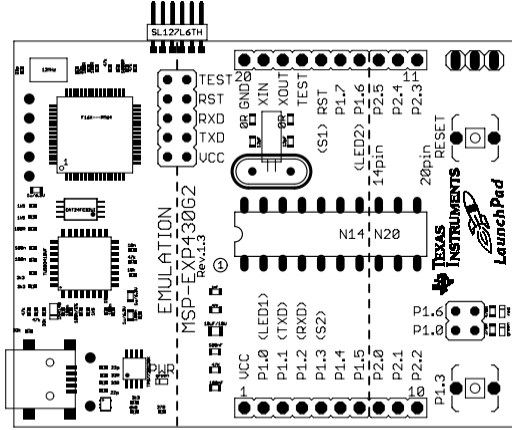


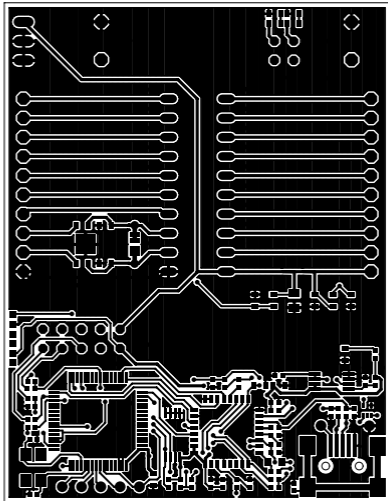


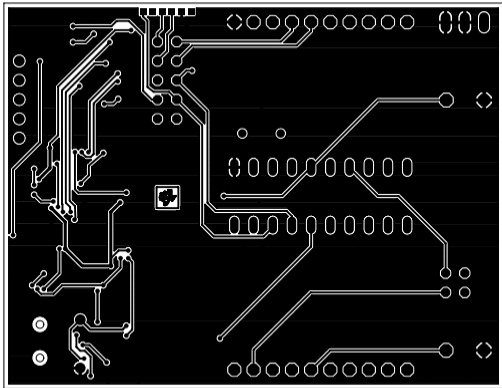
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TITLE: MSP-EXP430G2_Rev.1.4	
Document Number:	REV: 1.4
Date: 7/6/2010 3:42:53 PM	Sheet: 3/3











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